Broadcom's NUV-MT SiPM technology

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Broadcom at a Glance











One of the industry's broadest IP portfolios with >17,000 patents in FY22



22 Category-Leading Semiconductor and Infrastructure Software Divisions



From photodiode to SPAD

- p-n junctions in semiconductors are the basis of
 - Photodiodes

SPADs

– APDs

- Can be differentiated by gain
- Gain can be driven by reverse bias
- APD: Avalanche Photodiode internal gain 10 to 100
- SPAD: Single Photon Avalanche Diode Geiger mode internal gain up to 10M



Gain



From SPAD to SiPM

SPAD working in Geiger mode



Single SPAD discharge signal regardless of number of incident photons





SiPM Images





AFBR-S4N: NUV-MT SiPM

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	NUV-MT
Sensitivity range (nm)	250 to 900
Peak sensitivity (nm)	420
PDE at 420nm (%)	63
Gain (M)	7.3
DCR (kcps/mm ²)	120
SPAD pitch (µm)	40
CT (%)	23
AP (%)	1
τ _{recharge} (ns)	55
Typ. OV	12
Temp. coefficient (mV/°C)	30
Vbreak (V)	32.5



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NUV-MT: New Package Design

- Overmolded PCB with bond wire
- Focus:
 - Highest transmittance of mold compound in UV-blue
 - Long term stability (no yellowing)

SiPM chip

PWB

- High reliability & ruggedness
- Cost efficiency & Simple + Flexible supply-chain
- High Package Fill Factor

window cap 0.175 mm

0.1mm



Typical Backside (LGA)





11

1.25

NUV-MT: Overmold Material

- Candidates selected for best optical peformance over lifetime
 - 3000hrs at 120°C correspond to lifetime of about 20 years at 25°C





NUV-SiPM Product Summary & Outlook



*TIA module to be upgraded to NUV-MT



DEBROADCOM® connecting everything ®

Thank you!

Please come and talk to me in the industrial exhibit

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